



Product/Process Change Notice - PCN 12_0057 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: OP270 QMLV/QMLR Aerospace Models Change of Wafer Fab Site & Wafer Diameter

Publication Date: 07-Mar-2012

Effectivity Date: 05-Jun-2012 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

Change wafer fabrication location from Analog Devices, Inc Santa Clara 100mm (no longer in operation) to Analog Devices, Inc. Wilmington Massachusetts 150 mm fab facility. As a result of this transfer, a titanium-tungsten barrier layer is added under thin-film resistors to reduce noise susceptibility. NOTE: Commercial and QML Class Q models of the OP270 have already transferred to 150 mm (reference PCN 06_0059) in 2006. Note: Aerospace Die sales will also now be supplied from Wilmington 150 mm.

Reason For Change

Depletion of retained 100 mm wafer bank for aerospace models.

Impact of the change (positive or negative) on fit, form, function & reliability

Quality and reliability levels and electrical performance are not affected by these changes. All transferred product will have comparable or improved manufacturing process capabilities. ADI wafer fabs share many of the same process tools, equipment, and associated unit process steps. The TiW barrier layer under thin-film process has been previously qualified and has proven highly reliable on millions of shipped units. The TiW barrier metal layer is already in use on numerous products from the Wilmington, MA bipolar fab process.

Product Identification *(this section will describe how to identify the changed material)*

QMLV & QMLR Datecodes 12XX and higher (2012).

Summary of Supporting Information

Wafer Lot Acceptance per MIL-STD_883, TM5007, Group A,B,C, & E testing per MIL-PRF-38535 have been completed. All parameters (both tested & guaranteed), were re-verified during the initial commercial & Class Q product fab transfer in 2006. The Wilmington facility is certified to all major quality, environmental, health, and safety systems (including ISO 9001:2000, ISO 14001:2004, ISO/TS 16949:2002, OHSAS 18001:1999, and Class V MIL-PRF-38535).

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_12_0057_Rev_-_OP270_150mm_qual.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas:	PCN_Americas@analog.com	Europe:	PCN_Europe@analog.com	Japan:	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (8)

OP270S / 5962-8872101V2A	OP270S / 5962-8872101VDA	OP270S / 5962-8872101VPA	OP270S / 5962R8872101V2A	OP270S / 5962R8872101VDA
OP270S / 5962R8872101VPA	OP270S / OP2700000C	OP270S / OP270R000C		

Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	07-Mar-2012	Initial Release

Analog Devices, Inc.

DocId:1882 Parent DocId:None Layout Rev.6